

REPLY

To: Examiner of the Patent Office

1. Identification of the International Application: PCT/JP03/11943

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5. Content of Reply:

Claim 1 is amended as follows,

1. An engineering plastic cardboard, consisting of a core member and covering member(s) covering one or both side(s) of said core member, wherein at least said core member is made of crystalline polyester, stereoregular polyethylene, a polymer alloy of engineering plastic and thermoplastic resin, or a polymer alloy of said engineering plastic, said thermoplastic resin, and a rubber-like material, said engineering plastic being of one or more kinds(s) of engineering plastic(s) selected from a group of polyamide(PA), polyester(PE), polyacetal(POM), polycarbonate(PC), polyethylene terephthalate(PET), polybutylene terephthalate(PBT), polysulfone(PSF), polyethersulfone(PES), polyphenylene ether(PPE), modified polyphenylene ether(Modified PPE), polyphenylene sulfide(PPS), polyarylate(PAR), polyether-etherketone(PEEK), polyamideimide(PAI), polyimide(PI), polyetherimide(PEI), polyaminobismaleimide, methylpentene copolymer(TPX), crystalline polyester, and stereoregular polyethylene

The materials selected in said amended claim 1 have excellent heat resistance and moldability.

Accordingly, said cardboard of the present invention is useful as a sound absorbing material, and as a shock absorber for use in the engine area of a car, which is exposed to high temperatures.

**Comparison of the present invention with the Literatures cited.**

**(1) Literature 1(JITUGANSHOU47-62935)**

Literature 1 discloses a synthetic resin cardboard, but the use of the resin materials selected in said amended claim 1 is not disclosed in this Literature.

**(2) Literature 2(JP52-58693 A)**

Literature 2 discloses a cardboard made of a synthetic resin such as polyethylene, polypropylene, polyvinylchloride, polystyrene, ABS resin, or polyamide resin, but the use of the resin materials selected in said amended claim 1 is not disclosed in this Literature.

**(3) Literature 3(JP6-255007 A)**

Literature 3 discloses a sandwich board made of an engineering plastic such as polyphenylene oxide or the like, but the use of the resin materials selected in said amended claim 1 is not disclosed in this Literature.

**(4) Literature 4(JP2002-187226 A)**

Literature 4 discloses a hollow resin board made of polyethylene terephthalate, but the use of crystalline polyethyleneteraphtalate is not disclosed in this Literature.

**(5) Literature 5(JITUGANSHOU56-93220)**

Literature 5 discloses a board like structural material made of polycarbonate, but the use of a polymer alloy of polycarbonate and other thermoplastic resin, or a polymer alloy of polycarbonate, other thermoplastic resin and a rubber-like material is not disclosed in this Literature.

**(6) Literature6(JP7-243796 A)**

Literature 6 discloses a panel having polygon cell part made of high modulus synthetic resin such as polyurethane, p-aramide, ionomer, polycarbonate, fluorocarbon resin, polyolefin, polyetherimide or the like, but the use of the resin materials selected in said amended claim 1 is not

disclosed in this Literature.

### **Conclusion**

Since said cardboard of the invention of said amended claim 1 is made of the resin material selected in said amended claim 1, said cardboard has an excellent heat resistance and moldability, while said resin materials are not disclosed at all in Literatures 1 to 6.

Accordingly, the invention of said amended claim 1 has novelty and an inventive step.